**ON Semiconductor** 

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# Onsemi

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## MOSFET – Single, N-Channel, Small Signal, SC-70

## 30 V, 270 mA

#### Features

- Low Gate Charge for Fast Switching
- Small Footprint 30% Smaller than TSOP–6
- ESD Protected Gate
- AEC-Q101 Qualified and PPAP Capable NVS4001N
- These Devices are Pb-Free and are RoHS Compliant

## Applications

- Low Side Load Switch
- Li-Ion Battery Supplied Devices Cell Phones, PDAs, DSC
- Buck Converters
- Level Shifts

## **MAXIMUM RATINGS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise stated)

Paramo	Symbol	Value	Units		
Drain-to-Source Voltage			V <sub>DSS</sub>	30	V
Gate-to-Source Voltage			V <sub>GS</sub>	±20	V
Continuous Drain Current (Note 1)	<b>,,,</b>		Ι <sub>D</sub>	270	mA
	State	T <sub>A</sub> = 85 °C		200	
$ \begin{array}{c c} \mbox{Power Dissipation} & \mbox{Steady} \\ \mbox{(Note 1)} & \mbox{State} \end{array} T_{A} = 25 \ ^{\circ}\mbox{C} \\ \label{eq:table_eq} \end{array} $			PD	330	mW
Pulsed Drain Current t =10 μs			I <sub>DM</sub>	800	mA
Operating Junction and Storage Temperature			T <sub>J</sub> , T <sub>STG</sub>	–55 to 150	°C
Source Current (Body Diode)			I <sub>S</sub>	270	mA
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Surface mounted on FR4 board using 1 in sq. pad size (Cu area = 1.127 in sq. [1 oz] including traces).

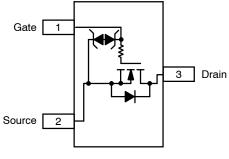


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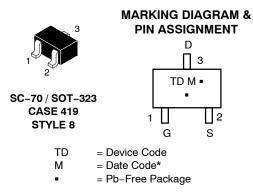
#### http://onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> TYP	I <sub>D</sub> Max
30 V	1.0 Ω @ 4.0 V	270 mA
30 V	1.5 Ω @ 2.5 V	270 1114

SC-70/SOT-323 (3 LEADS)



(Top View)



(Note: Microdot may be in either location) \*Date Code orientation may vary depending

upon manufacturing location.

#### **ORDERING INFORMATION**

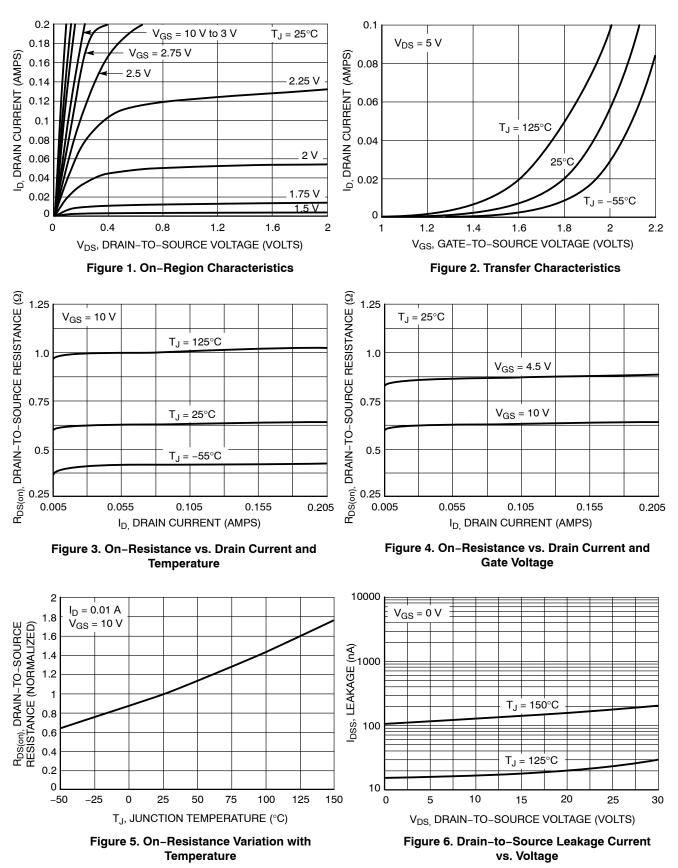
Device	Package	Shipping <sup>†</sup>
NTS4001NT1G	SC-70 (Pb-Free)	3000 / Tape & Reel
NVS4001NT1G	SC-70 (Pb-Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = $25^{\circ}$ C unless otherwise stated)

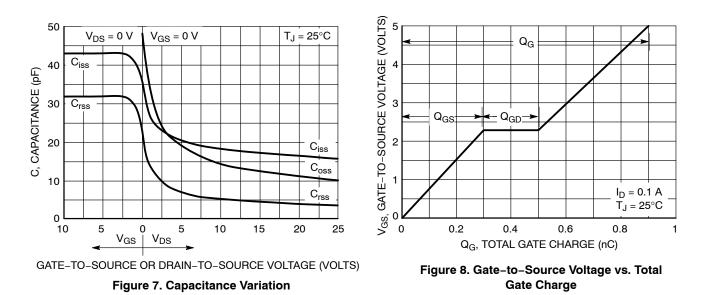
Parameter	Symbol	Test Con	dition	Min	Тур	Мах	Unit
OFF CHARACTERISTICS	1	•					
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 V, I_D$	= 100 μA	30			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>				60		mV/ °C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = 0 V, V <sub>I</sub>	<sub>DS</sub> = 30 V			1.0	μA
Gate-to-Source Leakage Current	I <sub>GSS</sub>	$V_{DS} = 0 V, V_{G}$	<sub>iS</sub> = ±10 V			±1.0	μA
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{D}$	) = 100 μA	0.8	1.2	1.5	V
Gate Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>				-3.4		mV/ °C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.0 V, I	<sub>D</sub> = 10 mA		1.0	1.5	Ω
		V <sub>GS</sub> = 2.5 V, I	<sub>D</sub> = 10 mA		1.5	2.0	-
Forward Transconductance	<b>9</b> FS	V <sub>DS</sub> = 3.0 V, I	<sub>D</sub> = 10 mA		80		mS
CHARGES AND CAPACITANCES	•						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1.0 MHz, V <sub>DS</sub> = 5.0 V			20	33	pF
Output Capacitance	C <sub>OSS</sub>				19	32	
Reverse Transfer Capacitance	C <sub>RSS</sub>				7.25	12	
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = 5.0 V, V <sub>DS</sub> = 24 V, I <sub>D</sub> = 0.1 A			0.9	1.3	nC
Threshold Gate Charge	Q <sub>G(TH)</sub>				0.2		-
Gate-to-Source Charge	Q <sub>GS</sub>				0.3		
Gate-to-Drain Charge	Q <sub>GD</sub>				0.2		
SWITCHING CHARACTERISTICS (No	te 3)					•	•
Turn-On Delay Time	td <sub>(ON)</sub>	V <sub>GS</sub> = 4.5 V, V <sub>DD</sub> = 5.0 V, I <sub>D</sub> = 10 mA, R <sub>G</sub> = 50 Ω			17		ns
Rise Time	tr				23		
Turn-Off Delay Time	td <sub>(OFF)</sub>				94		
Fall Time	tf				82		
DRAIN-SOURCE DIODE CHARACTE	RISTICS						
Forward Diode Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V,	$T_J = 25^{\circ}C$		0.65	0.7	V
		I <sub>S</sub> = 10 mA	T <sub>J</sub> = 125°C		0.43		
Reverse Recovery Time	t <sub>RR</sub>	$V_{GS} = 0 \text{ V, } dI_S/dt$ $I_S = 10$			5.0		ns

2. Pulse Test: pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2%. 3. Switching characteristics are independent of operating junction temperatures.



#### TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)

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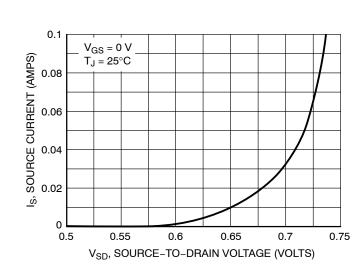
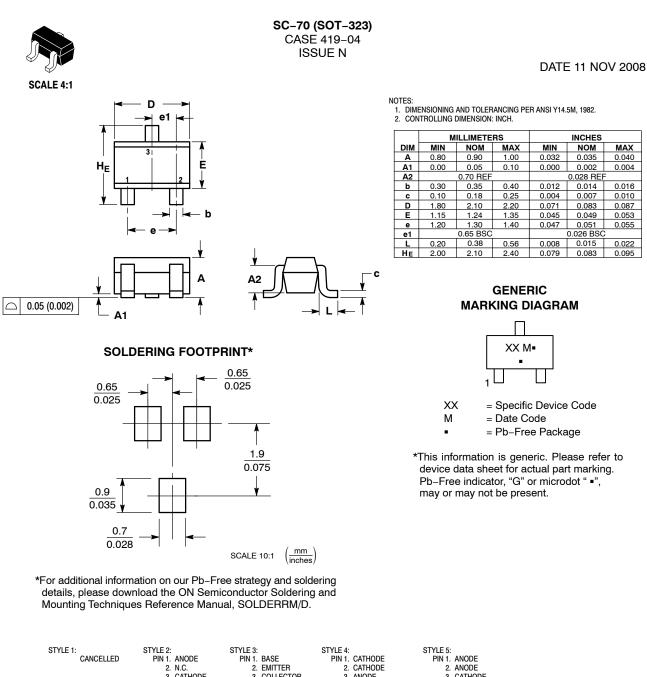


Figure 9. Diode Forward Voltage vs. Current





		3. CATHODE	3. COLLECTOR	3. ANODE	3. CATHODE	
3. COLLECTOR 3. COLLECTOR 3. DRAIN 3. CATHODE-ANODE 3. ANODE-CATHODE 3. CATHOD	PIN 1. EMITTER 2. BASE	PIN 1. BASE 2. EMITTER	PIN 1. GATE 2. SOURCE	PIN 1. ANODE 2. CATHODE	PIN 1. CATHODE 2. ANODE	Style 11: Pin 1. Cathode 2. Cathode 3. Cathode

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